Program

The 25th European Mask and Lithography Conference
EMLC 2009

January 12 – 15, 2009
Hilton Hotel
Dresden, Germany

www.EMLC2009.com
Welcome to the EMLC 2009 in Dresden

25th European Mask and Lithography Conference, EMLC2009
being held on January 12th to 15th 2009
at the Hilton Hotel, Dresden, Germany.

On behalf of VDE/GMM, the Sponsors, and the Organizing Committee, we would like to welcome you to the 25th European Mask and Lithography Conference, EMLC2009 at the Hilton Hotel in the city of Dresden. The conference has annually brought together scientists, researchers, engineers, and technologists from research institutes and companies from around the world to present innovations at the forefront of mask lithography and mask technology.

The technical conference is scheduled from Tuesday through Thursday and is dedicated to the science, technology, engineering and application of mask and lithography technologies and associated processes. Presenting an overview of the current status in mask and lithography technologies and of future strategies, this is the place where mask producers and users are made acquainted with newest developments and results.

On Monday evening we welcome you to an informal Get Together at the Hilton Hotel at 19:00.

On Tuesday and Wednesday, our traditional Technical Exhibition will take place. To foster the exchange between the conference attendees and the exhibitors, this will also be the place for all of our coffee and lunch breaks.

So, please enjoy the technical sessions of the EMLC2009 as well as the technical exhibition, but also allow yourself to visit Dresden, one of the most beautiful cities in Europe!

Conference Chair: Dr. U. Behringer (*), UBC Microelectronics, Ammerbuch, Germany

Co-Conference Chairs Mr. B. Grenon (*), Grenon Consulting, Colchester, VT, USA
Mr. N. Hayashi (*), DNP, Saitama, Japan

Program Chairs: Dr. W. Maurer (*), Infineon Technologies, AG, Munich, Germany
J. Waelpoel (*), ASML, Veldhoven, The Netherlands

Co-Program Chair: Mr. W. Montgomery (*), SEMATECH, Albany, NY, USA
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Members of the International Steering Committee of the EMLC and Members of the International Program Committee of the EMLC 2009(*)

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Mr. N. Hayashi (*), DNP, Saitama, Japan

Program Chairs: Dr. W. Maurer (*), Infineon Technologies AG, Munich, Germany
J. Waelpoel (*), ASML, Veldhoven, The Netherlands

Co-Program Chair: Mr. W. Montgomery (*), SEMATECH, Albany, NY, USA

Mr. F. Abboud, Intel Corp., Santa Clara, CA, USA
Dr. M. Arnz, Carl Zeiss SMT AG, Oberkochen, Germany (*)
Mr. E. Baracchi, ST Microelectronics, Agrate Brianza, Italy
Dr. C. Blaesing, Carl Zeiss SMS GMBH, Jena, Germany
Mr. P Chen, Taiwan Mask Corp., Hsinchu, Taiwan (*)
Dr. C. Constantine, Oerlikon USA Inc., St. Petersburg, FL, USA(*)
Prof. R. Engelstad, University of Wisconsin, Madison, WI, USA (*)
Mr. B.G. Eynon, Molecular Imprints, Austin, TX, USA (*)
Mr. D. Farrar, HOYA Corporation, LONDON, UK
Mr. C. Gale, Applied Materials, Dresden, Germany (*)
Mr. B. Grenon, Grenon Consulting, Inc., Colchester, VT, USA (*)
Mr. N. Hayashi, Dai Nippon Printing Co. Ltd., Saitama, Japan (*)
Mr. R. Jonckheere, IMEC, Leuven, Belgium (*)
Dr. C.K. Kalus, Synopsys GmbH, Aschheim, Germany (*)
Mr. K.R. Kimmel, AMTC, Dresden, Germany(*)
Ms. B. Lauche, Photronics MZD GmbH, Dresden, Germany
Dr. H. Loeschner, IMS Nanofabrication AG, Vienna, Austria (*)
Mr. B. Naber, Cadence Design Systems Inc., San Jose, USA (*)
Dr. Ch. Pierrat, Cadence Design Systems Inc., San Jose, USA (*)
Dr. E. Rausa, Oerlikon USA Inc., Saint Petersburg, FL, USA (*)
Dr. C. Reita, CEA-LETI, Grenoble, France
Mr. D. J. Resnick, Molecular Imprints, Austin, TX, USA (*)
Dr. F. Reuther, micro resist technology GmbH, Berlin, Germany
Dr. C. Romeo, ST-Microelectronics, Agrate Brianza, Italy (*)
Mr. K. Ronse, IMEC, Leuven, Belgium
Prof. H. Scheer, University of Wuppertal, Germany (*)
Mr. Gerd Scheuring, Mue Tec GmbH, Munich, Germany
Dr. R. Schnabel, VDE/VDI-GMM, Frankfurt, Germany (*)
Mr. M. Staples, AMD Saxony LLC & Co. KG, Dresden, Germany
Mrs. I. Stolberg, Vistec Electron Beam GmbH, Jena, Germany (*)
Dr. S. Tedesco, CEA-LETI, Grenoble, France (*)
Mr. M. Tissier, Toppan Photomasks S.A., Roussset, France (*)
Mr. G. Unger, Qimonda GmbH & Co. OHG, Dresden, Germany (*)
Mr. J.T. Weed, SYNOPSYS, Inc., Mountain View, CA, USA
Mr. J. Whittey, Vistec Semiconductor Systems, Oakdale, USA (*)
Mr. H. Wolf, Photronics MZD GmbH, Dresden, Germany (*)
Mr. S. Wurm, SEMATECH, Albany, NY, USA(*)
Mr. L. Zurbrick, Agilent Technologies, Santa Clara, CA, USA (*)
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Cover picture:
Courtesy of Toppan Photomasks
Program Overview

Monday, January 12th, 2009

16:00  Set-up for the Technical exhibition

17:00  EMLC Steering and Program Committee Meeting
       on invitation only

18:00 - Check in / Registration
       19:30

19:00  Get Together Reception

Tuesday, January 13th, 2009

09:15  Welcome and Introduction
       U. Behringer, UBC Microelectronics,
       Ammerbuch, Germany, Conference Chair

09:25  Invited Welcome Speaker
       D. Hilbert, Mayor of Economic Affairs of the City
       of Dresden

Plenary Session I

       Session Chairs:
       W. Maurer, Infineon Technologies AG,
       Munich, Germany
       U. Behringer, UBC Microelectronics,
       Ammerbuch, Germany

09:55  Keynote 1:
       Lithography Development and Research for
       the ≤ 22nm Half-Pitch
       S. Wurm, SEMATECH, Albany, NY, USA

10:25  Mask Industry Assessment Trend Analysis
       (invited)
       G. Hughes, Sematech, Albany, NY, USA
       H. Yun, Sematech, Albany, NY, USA

10:50  Coffee Break
Plenary Session II

Session Chairs:
W. Maurer, Infineon Technologies AG, Munich, Germany;
J. Waelpoel, ASML, Veldhoven, The Netherlands

11:20 Keynote 2: Mask Salvage in the Age of Capital Contraction
K. Kimmel, AMTC, Dresden, Germany

11:50 Best Paper from PMJ 2008 Effects of Mask Absorber Thickness on Printability in EUV Lithography with High Resolution Resist (invited)
T. Kamo, H. Aoyama, T. Tanaka and O. Suga
MIRAI - Semiconductor Leading Edge Technologies, Inc., Japan

12:20 Best Poster of BACUS 2008 (invited) Deflection Unit for Multi-Beam Mask Masking
F. Letzkus, J. Butschke, M. Irmscher, M. Jurisch, W. Klingler, IMS Chips, Stuttgart, Germany;
E. Platzgummer, Ch. Klein, H. Loeschner, R. Springer, IMS Nanofabrication AG, Vienna, Austria

12:50 Lunch Break

Session 3 Mask Business & Application
Session Chairs:
H. Wolf, Photronics, Dresden, Germany;
M. Tissier, Toppan Photomask, Rousset, France

14:10 Do Masks really matter? (invited)
C. Progler, M. Graham, Photronics Inc., Brookfield, USA.

14:40 SEMATECH Mask Program
H. Yun, SEMATECH; Albany, NY, USA
15:00  Mask parameter variation in the context of the overall variation budget of an advanced logic wafer FAB (invited)
R. Seltmann, A. Parge, J. Busch, T. Hertzsch, A. Poock, AMD FAB36 LLC & Co.KG, Dresden, Germany

15:30  Coffee Break

Session 4  Simulation & Double Patterning
Session Chairs:
M. Arnz, Carl Zeiss, SMT AG, Oberkochen, Germany;
W. Maurer, Infineon Technologies, Munich, Germany

16:00  Extended Abbe approach for fast and accurate lithography imaging simulations
P. Evanschitzky, T. Fühner, A. Erdmann, Fraunhofer Institute Integrated Systems and Device Technology (Fraunhofer IISB), Erlangen, Germany

16:20  Decomposition Algorithm for Double Patterning of Contacts and Via Layers
A. El-Gamal, M. Al-Imam, Mentor Graphics Cairo, Egypt

16:40  Mask contribution on CD & OVL errors budgets for Double patterning lithography
I. Servin\textsuperscript{a}, C. Lapeyre\textsuperscript{a}, S. Barnola\textsuperscript{a}, B. Connolly\textsuperscript{b}, R. Ploss\textsuperscript{b}, K. Nakagawa\textsuperscript{c}, P. Buck\textsuperscript{c}, M. McCallum\textsuperscript{d}
\textsuperscript{a}CEA-Leti Minatec, Grenoble, France
\textsuperscript{b}Toppan Photomasks Inc., Dresden, Germany
\textsuperscript{c}Toppan Photomasks Inc. Gresham, Oregon, USA
\textsuperscript{d}Nikon Corporation, Livingston, Scotland
17:00 A new method and process based on vacuum technology for photomask decontamination
J.M. Foray¹, S. HadjRabah¹, J. Palisson¹, M. Davenet¹, A. Favre¹, P. Sergent², R. Schroeder², M. Tissier², V. Baudiquez³, P. Nesladek³, S. Gopalakrishnan³, I. Hollein³, F. Dufaye⁴, S. Gough⁴
¹ Alcatel Vacuum Technology, Annecy, France; ² Toppan, Photomasks S.A., Rousset, France ³ AMTC, Dresden, Germany

17:20 Particle transport and reattachment on a mask surface
P. Nesladek⁵, S. Osborne⁶
⁵ Advanced Mask Technologies Center, Dresden, Germany ⁶ Sigmameltex Ltd, Shimoasao, Asao-ku Japan

17:40 Contamination control for ArF photo masks
J. S. Gordon⁷, M. Silova⁸, B. Connolly⁷, J. Huijbregtse⁸, N. Maxim⁸, L. Frisa⁷, C. Chovino⁷, C. Weins⁷
⁷ Toppan Photomasks, Inc., Round Rock, Texas, USA ⁸ ASML Netherlands B.V., Veldhoven, The Netherlands

18:00 End of presentation


19:00 Departure from the Hilton

19:30 River Cruise starts

22:45 River Cruise ends
Wednesday, January 14th, 2009

Session 6  EUV 1

Session Chairs:
B. Eynon, Molecular Imprints Inc.
Austin, TX, USA
R. Engelstad, University of Wisconsin,
Madison, WI, USA

09:20  Lithography light source challenges for Double Patterning and EUVL (invited)
N. Farrar, Cymer Inc., San Diego, CA, USA

09:50  The task of EUV-reflectometry for HVM of EUV-masks: first steps
A. Farahzadi, AIXUV GmbH, Aachen, Germany

10:10  EUV and DUV scatterometry for CD and edge profile metrology on EUV masks
B. Bodermann, Physikalisch-Technische Bundesanstalt (PTB), Braunschweig, Germany

10:30  EUV imaging performance - moving towards production
E. van Setten, ASML Netherlands B.V., Veldhoven, The Netherlands

10:50  Coffee Break

Session 7  NIL

Session Chairs:
D. Resnick, Molecular Imprints Inc. Austin, TX, USA; H. Scheer, University of Wuppertal, Germany

11:30  Resolution capability of EBM-6000 and EBM-7000 for Nano-imprint template
S. Yoshitake, NuFlare Technology Inc., Japan

11:50  Electron Beam inspection methods for imprint lithography at 32 nm
K. Selinidis, Molecular Imprints Inc., USA
12:10 UV NIL template making and imprint evaluation  
S. Sasaki, Dai Nippon Printing Co. Ltd., Japan

12:30 Residual-free imprint for sensor definition  
A. Mayer, University of Wuppertal, Germany

12:50 Lunch break

Session 8  Metrology  
Session Chairs:  
J. Whittey, Vistec Semiconductor Systems, Oakdale, CA, USA;  
C. Blaesing, Carl Zeiss SMS GmbH, Jena, Germany

14:20 Monte-Carlo Simulations of Image Analysis for flexible and high-resolution Registration Metrology  
M. Arnz, Carl Zeiss AMT AG, Oberkochen, Germany

14:40 SEM image contrast modeling for mask and wafer metrology  
C.G. Frase, Physikalisch-Technische Bundesanstalt (PTB), Braunschweig, Germany

15:00 Registration metrology on double patterning reticles  
K.-H. Schmidt*, K.-D. Röth*,  
F. Laskea*, J. Bender*,  
D. Adam*, O. Ache*  
*Vistec Semiconductor Systems GmbH, Weilburg, Germany

15:20 Reduced Pellicle Impact on Overlay using High Order Intrafield Grid Corrections  
R. de Kruif, ASML Netherlands B.V., Veldhoven, The Netherlands

15:40 Coffee Break
Session 9 ML2
Session Chairs:
I. Stolberg, Vistec Electron Beam GmbH, Jena, Germany; S. Tedesco, CEA/Leti, Grenoble, France

16:20 High Resolution Cell Projection
U. Weidenmüller, Vistron Electron Beam GmbH, Jena, Germany

16:40 Mapper: High Throughput Maskless Lithography
B. J. Kampherbeek, MAPPER Lithography B.V., Delft, The Netherlands

17:00 New writing strategy in electron beam direct write lithography to improve critical dense lines patterning for sub-45nm nodes
L. Martin, CEA-LETI, MINATEC, Grenoble, France

17:20 A solution to Meet New Challenges on EBDW Data Prep

18:00 Poster Reception
Session Chairs:
C. Gale, Applied Materials, Dresden, Germany; W. Montgomery (*), SEMATECH, Albany, NY, USA

Innovative processes investigation for photomask pod conditioning and drying
J.M Foray, Alcatel Vacuum Technology, Annecy, France

High speed (>100 Gbps) key components for a scalable optical data link, to be implemented in future maskless lithography applications
A. Paraskevopoulos, Fraunhofer Institut für Nachrichtentechnik - Heinrich Hertz Institut (HHI) Berlin, Germany
Molecular dynamics study on mold fracture by nano scale defects in nanoimprint lithography  
K. Tada, Osaka Prefecture University, Japan

Advanced proximity matching with Pattern Matcher  
A. Serebryakov, ASML Netherlands B.V., Veldhoven, The Netherlands

Mounting Methodologies to Measure EUV Reticle Nonflatness  
R. Engelstad, University of Wisconsin - Madison, WI, USA

CDP - Application to focus drilling  
S. Geisler, IHP GmbH, Frankfurt/Oder, Germany

MeRiT® repair verification using in-die phase metrology Phame®  
U. Buttgereit, Carl Zeiss SMS GmbH, Jena, Germany

Design Verification for sub 70 nm DRAM nodes via Metal Fixing using E-Beam Direct Write  
K. Keila*, P. Jaschinsky², C. Hohle¹, K.-H. Cho³, R. Schneider⁴, M. Tesauro⁴, F. Thrum², R. Zimmermann² and J. Kretzb²  
¹Fraunhofer Center for Nanoelectronic Technologies (CNT)  
²Qimonda Dresden GmbH & Co. OHG, Dresden, Germany  
³Qimonda AG, Neubiberg, Germany

Focus on DFM Photomask Input for EDA Workflow  
E. Beisser, Xyalis, Grenoble, France

Focus on High Quality and Availability of Photomasks in Advanced Lithography Environments  
M. Davenet et. al, AVTF, France

Focus on Development of Innovative Flow and Metrology for Photomasks Qualification  
P. Chini, Atmel, France

19:30 Dinner at the Hilton
Thursday, January 15th, 2009

Session 10: Insp. & Pattern Generation

Session Chairs:
G. Unger, Qimonda, Dresden, Germany
E. Rausa, Oerlikon, Saint Petersburg, FL, USA

09:20 Improving yield and cycle time at the inspection process by means of a new defects disposition technique
E. Villa, DNP Photomask Europe, Agrate Brianza, Milano, Italy

09:40 Nuisance Event Reduction Using Sensitivity Control Layers (SCL) for Advanced Photomask Inspection
S. Hedges, Photronics nanoFab North America, Boise ID, USA

10:00 Increasing inspection equipment productivity by utilizing Factory Automation SW on TeraScan 5XX systems
T. Jakubski, AMTC, Dresden, Germany

10:20 Error-budget paradigms and laser mask pattern generator evolution
C. Hamaker, Applied Materials, Hillsboro, OR, USA

10:40 Coffee Break

Session 11 EUV 2

Session Chairs:
S. Wurm, SEMATECH, Albany, NY, USA; H. Yun, SEMATECH, Albany, USA

11:10 Defect Mitigation and Reduction in EUVL Mask Blanks
R. Randive, SEMATECH, Albany, USA

11:30 EUV Actinic Defect Inspection and Defect Printability at sub-32 nm Half-pitch
S. Huh, SEMATECH, Albany, USA
11:50 An Overview of Electrostatic Chucking for EUV Lithography  
*R. Engelstad, University of Wisconsin – Madison, WI, USA*

12:10 Sub-30nm defect removal on EUV substrates  
*A. Rastegar, SEMATECH, Albany, NY, USA*

12:30 Farewell

12:40 End of Conference

12:40 Farewell Lunch

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**Company Visits on Thursday January 15th 2009**

14:10 Bus leaves for AMD or Qimonda from the Hilton Hotel

**at AMD:**

- company presentation  
- Dr. Rolf Stephan, Senior Manager Process Integration:  
  “45nm and 32nm High Performance CMOS Technologies at AMD”  
- AMD campus tour (e.g. Material Lab)

*max. number of participants: 25*  
*duration: 3 – 3.5 h*  
*(~ 1h presentation / ~ 2h campus tour)*

*start time: 14:30 at AMD*  
*end time: 17:30*  
*Bus will be back at the Hilton around 18:00*

**at Qimonda:**

- company presentation  
- Thomas Zell, Senior Principal Engineer Lithography  
  “Qimonda Lithography & Mask Highlights”  
- window tour

*max. number of participants: 20*  
*duration: 2.0 h*  
*(45’ presentation incl. questions / 45’ line tour)*  
*start time: 14:30 at Qimonda*  
*end: time: 16:30*  
*Bus will be back at the Hilton around 17:00*
### CONFERENCE INFORMATION

#### CONFERENCE HOURS

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#### REGISTRATION HOURS

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<td>08:00 h to 12:00 h</td>
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#### TECHNICAL EXHIBITION

Parallel to the conference presentations on Tuesday and Wednesday we offer you to take part in a technical exhibition. There is space for about 25 exhibitors. Presentation tables and pin boards will be available.

If you intend to participate in the technical exhibition as an exhibitor, please contact the chairperson as soon as possible as the exhibition area is limited (please use the enclosed registration form).

UBC Microelectronics, Dr. Uwe Behringer
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E-Mail: uwe.behringer.ubc@t-online.de

### INFORMATION FOR AUTHORS

#### YOUR PRESENTATION AND CV

The most convenient way for you and the organizers is to provide your slides in the form of MS-Powerpoint format (ppt) on a USB-stick. As early as possible, but latest during the break before your session, you should download and test them on the presentation computer. Your Session Chair will surely be glad to assist you. You may also use your own laptop computer, but experience has shown to do better not.

Please send in - if not yet done - your short CV to the Conference Chairs and to your Session Chair, so that he may introduce you appropriately to the audience.
MANUSCRIPTS AND PROCEEDINGS

Manuscripts should be sent as soon as possible (deadline: January 13th 2009) to the Program- and the Conference Chairpersons:
Dr. Uwe Behringer: uwe.behringer.ubc@t-online.de,
Dr. Wilhelm Maurer,: wilhelm.maurer@infineon.com,
Mr. Jacques Waelpoel,: jacques.waelpoel@asml.nl.

Since the manuscripts will be directly reproduced in the proceedings, please send them as a pdf-file by e-mail. The manuscripts should be between 6 and 12 pages (figures included). Please follow the formatting and further guidelines provided in the sample manuscript under: www.emlc2009.com

Again, your last chance of delivering the manuscript will be the first day of the conference, Tuesday, January 13, 2009. Unless manuscripts are delivered until the first day of the conference, they will not be published in the combined SPIE/VDE volume and will not be a part of the SPIE Digital Library.

Each attendee of the conference will receive one copy of the proceedings as a CD which will be sent after the event.

BEST PAPER BEST POSTER AWARD

All conference attendees will elect the best paper and the best poster of the EMLC 2009. Manuscripts not received until the first day of the conference can not be elected for best paper resp. best poster.
**POSTER SESSION**

Poster size shall not exceed 120 cm (48") in width and 150cm (59") in height. The international paper format A0 fits perfectly. Please use text and figures of appropriate size (recommended text size >30 points) to make your poster readable from at least 1m / 1 yard distance. The use of color and extensive graphics is particularly encouraged. Alone a print-out of the manuscript does not serve the purpose of a poster presentation.

Please mount your poster on the provided stands as soon as Tuesday morning and do not dis-mount it before Thursday noon. This will enable the conference participants to view the posters before and after the poster session (Wednesday late afternoon) and will grant you a good deal of feedback to your work. The conference organisation will provide appropriate mounting material.

For further questions, please do not hesitate to contact the Poster Session Chairs: Chris_Gale@amat.com and Uwe.Behringer.ubc@t-online.de

**EXCURSION TO AMD or QIMONDA**

AMD, Qimonda and EMLC2009 have organized an informational tour of their Fabs in Dresden. A bus will leave the Dresden Hilton at 2:10 pm on Thursday, January 15th 2009.

Please sign in for these surely exceptional tours at the EMLC2009 Website or use the attached registration form. We ask for your understanding that the number of participants has to be limited and that participation will be on a first-come first-served basis.

**SPOUSE PROGRAM**

We would like to offer a city walk tour with an excellent city guide. To sign up, please stop at the registration desk. (Minimum persons 5).
GENERAL INFORMATION

EMLC 2009 SECRETARIAT

For detailed information please contact:

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fax: ++49 (0)69-6308-9828
e-Mail: gmm@vde.com

During the conference:
Tel: ++49 171 4695 118

CONFERENCE FEES

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<thead>
<tr>
<th></th>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>Non-Members</td>
<td>€ 700.00</td>
<td>€ 750.00</td>
</tr>
<tr>
<td>VDE, VDI Members*</td>
<td>€ 660.00</td>
<td>€ 710.00</td>
</tr>
<tr>
<td>Lecturer</td>
<td>€ 660.00</td>
<td>€ 710.00</td>
</tr>
<tr>
<td>Non-Member-Students**</td>
<td>€ 80.00</td>
<td>€ 100.00</td>
</tr>
<tr>
<td>Student Members**</td>
<td>€ 40.00</td>
<td>€ 60.00</td>
</tr>
<tr>
<td>Additional ticket for river cruise</td>
<td>€ 90.00</td>
<td>€ 90.00</td>
</tr>
</tbody>
</table>

* Participants claiming for the membership fee must attach a copy of their membership card to the registration form.

** A photocopy of the student card must be attached.

The conference fee includes admission to all sessions as well as to the daily coffee-breaks, one copy of the CD-ROM-proceedings, lunches, dinners and one ticket for the river cruise.

CONFERENCE REGISTRATION

To register for EMLC 2009, please fill in the registration form attached to this program and return it to VDE Conference Services, Stresemannallee 15, 60596 Frankfurt, Gemany. To benefit from the “early-bird-discount”, VDE Conference Services must receive the form before Dec. 19, 2008. Full payment or credit card information must accompany all registrations in order to be accepted. Completed forms may be sent by fax (++49 (0)69 96 31 5213) or e-mail (vde-conferences@vde.com). A confirmation of the registration will be sent upon receipt of full payment.
ONLINE REGISTRATION
Registrations for the conference and payment by credit card may be done online. Please, see the conference homepage www.EMLC2009.com

PAYMENT OF CONFERENCE FEE
Payment for registration, including bank charges and processing fees, must be made in Euro.

The conference fee has to be fully paid in advance. Your registration can only be confirmed if VDE-Conference Services has recorded receipt of your full payment. The following methods of payment are accepted:

- Payment by credit card authorisation as per registration form. The 16 digit card number, expiry date, security No. (last 3 digits on rear side of credit card) and holder's name must be indicated on the registration form. Signature of the card holder is mandatory.

- Cash payment on-site in EURO (€)

CANCELLATION
In case of cancellation, provided that written notice has been given to VDE-Conference Services before Dec. 19, 2008, the registration fee will be fully refunded less a handling fee of EURO 60.00. After Dec. 19, 2008, no refund will be made. Proceedings and CD-ROM-proceedings will then be sent to the registrant after the conference.

PROCEEDINGS
All papers accepted for presentation at the conference will be published with the proceedings CD-ROM. The proceedings will be sent after the conference to all delegates attending the event.

CONFERENCE VENUE
Hilton Dresden, An der Frauenkirche 5, 01069 Dresden, Germany, Phone: +49 (0)351/86420, Fax: +49 (0)351/8642-725, http://www.hilton.com/

Hilton Dresden, located in the heart of the old town, next to the Frauenkirche, is situated on Bruehl's Terrace. The Semper Opera House and the world-renowned "Zwinger"
are within walking distance. The piers of the world's largest and oldest paddle steamer fleet are next to the hotel.

TRANSPORT

By Air

*Dresden Airport*

From Dresden Klotzsche Airport, follow signs to city centre. After passing the Elbe Bridge, turn right onto Terrassenufer. From here, follow signs to the Hilton Dresden hotel. The 5-mile journey normally takes about 20 minutes from the airport to the hotel forecourt.

Getting to and from Dresden airport:

- **Bus Service**, typical minimum charge is EURO 8,00
- **Limousine**, typical minimum charge is EURO 70,00
- **Taxi**, typical minimum is EURO 25,00

**By train**

- from Frankfurt in 5 hours
- from Berlin in 3 hours
By car
From the A14/A4 (coming from Chemnitz/Leipzig), take exit 78 towards Dresden Altstadt. Follow the B6 signs in direction of Zentrum. At the Bremer/Hamburger Strasse junction, turn left into Bremer Strasse. Drive along the Elbe riverbank until you see signs for the Hilton Dresden hotel on your right. The 4-mile journey normally takes around 10 minutes from exit 78 to the hotel forecourt.

PARKING
The hotel car park has got 150 spaces. Parking costs EURO 19.00 per day. There is a valet service at no extra charge. Please book your parking space when booking your room at the hotel.

HOTEL RESERVATION
A block of rooms has been reserved for the EMLC 2009 participants at the Hilton Hotel Dresden.

The special hotel room rates are:

- SINGLE HILTON GUEST ROOM rates from 119.00 EUR
- TWIN HILTON GUEST ROOM rates from 119.00 EUR
- QUEEN HILTON GUEST ROOM rates from 119.00 EUR
- TWIN HILTON DELUXE ROOM rates from 144.00 EUR
- TWIN HILTON EXECUTIVE rates from 174.00 EUR

per night, including breakfast.
Additional person 25.00. EURO per night.

Accommodation is NOT included in the conference fee.

For reservation please contact the Hilton Hotel or go to the conference website: www.emlc2009.com

Hilton Dresden, An der Frauenkirche 5, 01069 Dresden, Germany,
phone: +49 (0)351/86420, fax: +49 (0)351/8642-725,
e-Mail: info.dresden@hilton.com
http://www.hilton.com/

You should reserve your rooms by December 19th, 2008, as after that date our rooms blocked at a group rate might be released by the hotel for general reservations. Please use the following code for booking: “EMLC 2009”.

All payments related to accommodation have to be made in the hotel before departure.
INTERNET ACCESS

The Hilton Hotel provides an Internet access at € 17,- per 24 hours (per day). You might also buy Internet access cards at a price of € 10,- for 60 minutes. In this case the clock will stop as soon as you terminate the Internet access. You can use this Internet access at any place of the Hilton hotel and, according to our information, in most Hilton Hotels world wide.

INSURANCE

The organisers may not be held responsible for any injury to participants or damage, theft and loss of personal belongings.

PASSPORT AND VISA REQUIREMENTS

Foreign visitors entering Germany have to present a valid Identity Card or Passport. Delegates who need a visa should contact the German consular offices or embassies in their home countries. Please note that neither the VDE-Conference Services nor the VDE/VDI-Society Microelectronics, Micro- and Precision Engineering (GMM) or the supporting bodies are able to extend any "Invitation" for application of visa.

ABOUT DRESDEN

The Elbe and the charming landscape between Saxon Switzerland and Meissen determine the nature in which the city on the Elbe river is embedded. The climate is equally beneficial for the development of the arts and for viniculture. The inhabitants are known for their own special charm, Saxon hospitality is proverbial.

At the same time Dresden is a modern city with the flair of the former Saxon residence – simply a place with life style. Many million guests visit Dresden every year.

More information you can find at: http://www.dresden.de
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